DC/DC Module Technology and Trend

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First. History of DC/DC Module

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1. Vicor: first full brick module



Features

- · RoHS Compliant (with F or G pin option)
- DC input range: 36 75 V
- · Input surge withstand: 100 V for 100 ms
- DC output: 3.3 48 V
- · Programmable output: 10 to 110%
- · Regulation: ±0.3% no load to full load
- · Efficiency: Up to 89%
- · Maximum operating temp: 100°C, full load
- · Power density: up to 100 W per cubic inch
- · Height above board: 0.43 in. (10,9 mm)
- · Parallelable, with N+M fault tolerance
- · Low noise ZCS/ZVS architecture





2. Lucent: first half brick module before 20 years



size: 61.0 mm x 57.9 mm x 12.7 mm (2.40 in. x 2.28 in. x 0.50 in.)



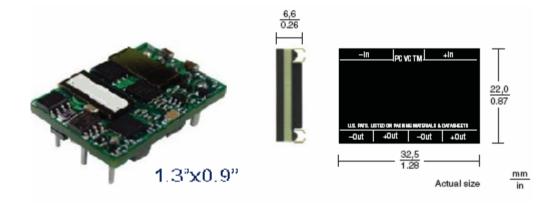
3、Then 1/4、1/8 brick







4、1/16 brick before one or two years





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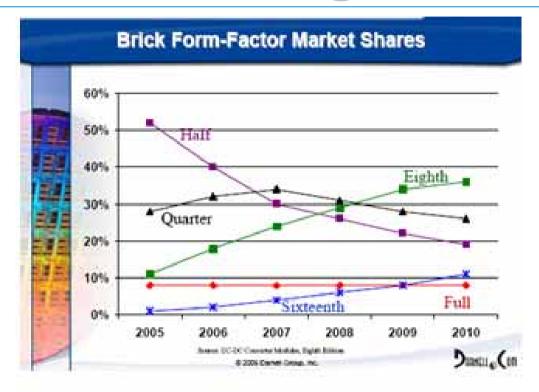
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Second. Marketing information



From Market forecast:
Eighth /Sixeteen brick rise
Others fall



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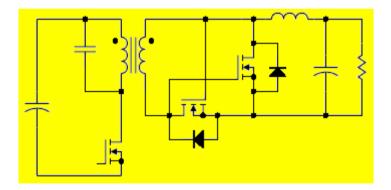
Fourth. Summary



First: Topology

1、Resonant Tech1: forward resonant

Lm & C resonant

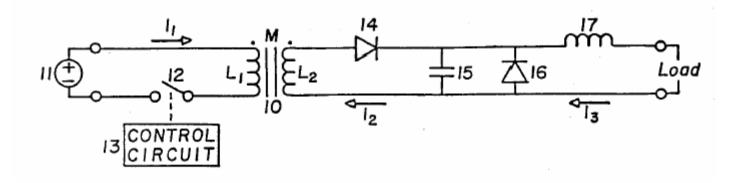


Old tech: fsw low, or else power loss much larger



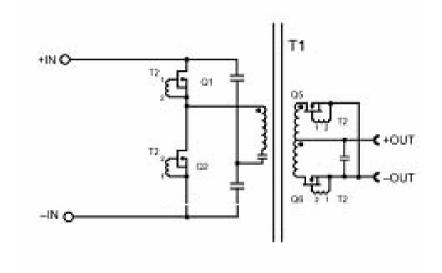
1、Resonant Tech2:

Vicor Patent, US4415959 Patent Expired





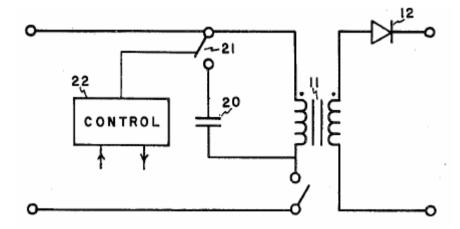
1、Resonant Tech3: LLC resonant





2. Active Clamp: G1

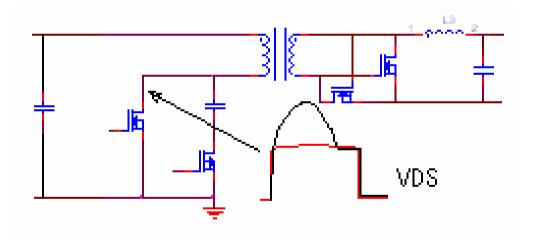
Vicor patent, US4441146, Apr.3,1984 Patent Expired;





2. Active Clamp: drive from Active clamp G1

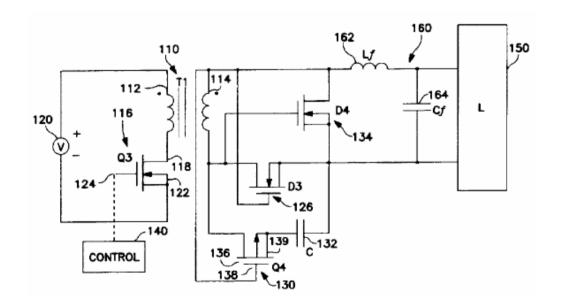
Gores/Tyco/Lucent patent, US5303138





2. Active Clamp: G2

IPD patent, US5781420/6278621, Jul.14,1998

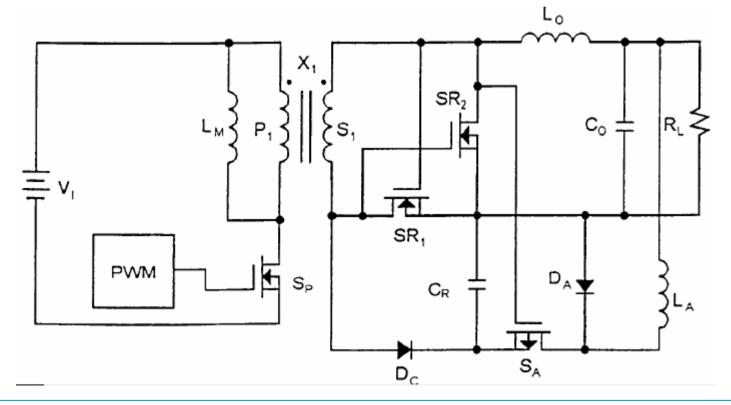


Bibliographic Data			
Application Number:	08/730,684	Customer Number:	
Filing or 371 (c) Date:	10-11-1996	Status:	Patent Expired Due to NonPayment of Maintenance Fees Under 37 CFR 1.362
Application Type:	Utility	Status Date:	08-16-2006
Examiner Name:	JARDIEU, DEREK	Location: 0	FILE REPOSITORY (FRANCONIA)
Group Art Unit:	2838	Location Date:	12-30-1999
Confirmation Number:	5690	Earliest Publication No:	
Attorney Docket Number:	IPD-001	Earliest Publication Date:	
Class / Subclass:	363/021	Patent Number:	5,781,420
First Named Inventor:	GANG XIA , BEDFORD, MA (US)	Issue Date of Patent:	07-14-1998



2. Active Clamp: G3

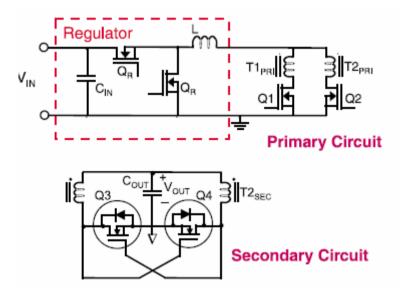
US6239989, May, 29, 2001;





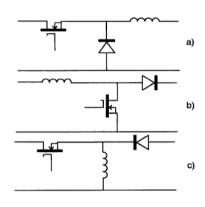
3、Two stage 1

Key Technologies: Two-stage buck and current-driven push-pull converter topology, synchronous rectifiers, ZVS and ZCS on output rectifiers, PCB, magnetics. (Synqor patent)

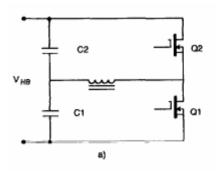


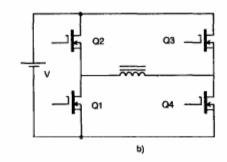


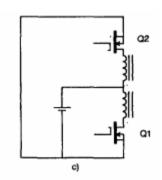
3、Two stage 2



- 1)fsw of second stage is larger
- 2)fixed frequency resonant



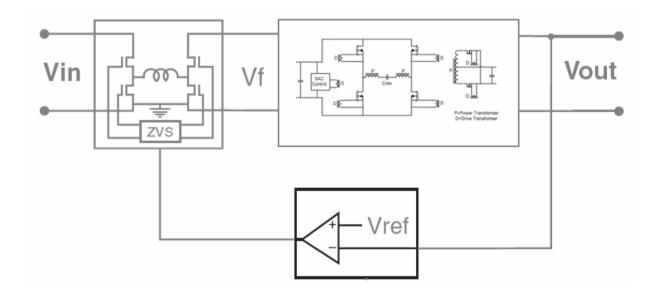






3. Two stage 3:

Pre regulator+LLC resonant , fsw=?MHZ





4. Other topology:

Shift phase full bridge: Duty lose

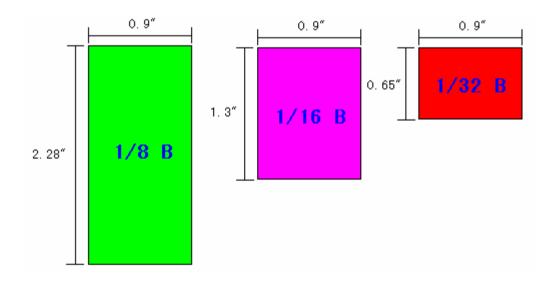
AHB: narrow source and load

Double Current: Magnetic Intergration | L&L



Second: Product

1、1/8 B-rick——>1/16 Brick——>1/32 Brick



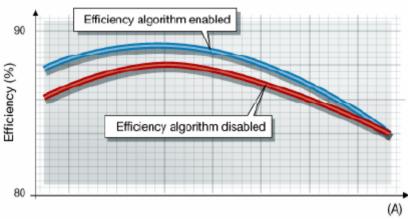
Reference: Digital Control Technologies for Modular DC-DC Converters



2. Digital control

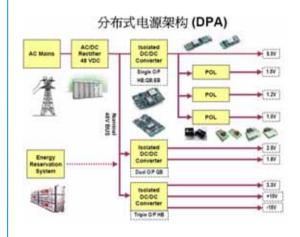


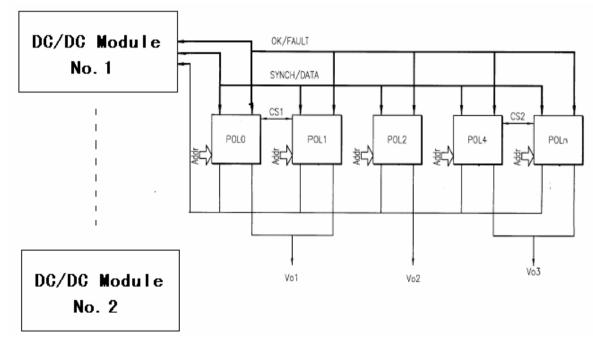
- Reduced power dissipation due to adaptive dead-time control
- Ability to adjust the output voltage
- Programmable droop for enhanced current sharing performance
- Increased flexibility and faster implementation of design changes
- Option of digital power management interface without size penalty



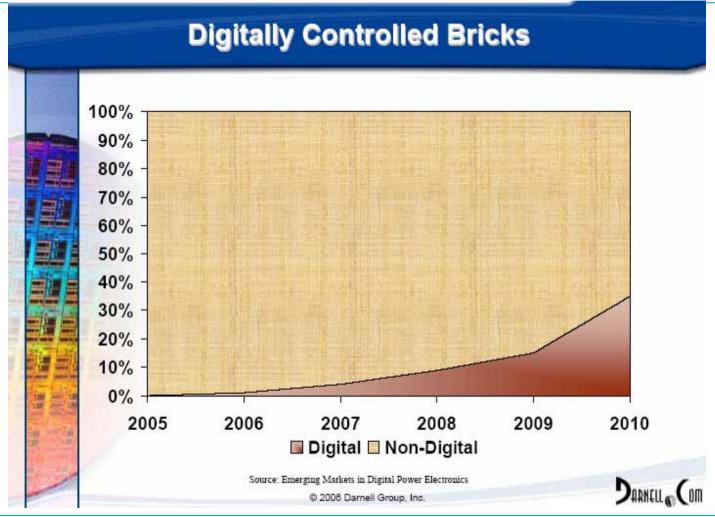


Easy to comunication: BUS<->POL BUS<->BUS









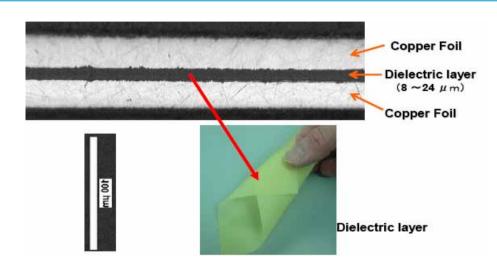


3, Advanced PCB Material

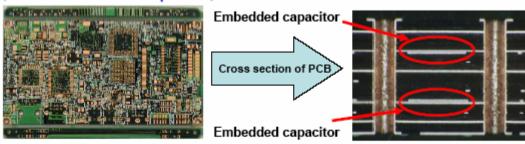
1)super thin PCB

Fr4_24um,16um,8um Copper foil_2oz

buried resister and capacitor







※Embedded capacitor is constructed into PCB as a condenser.

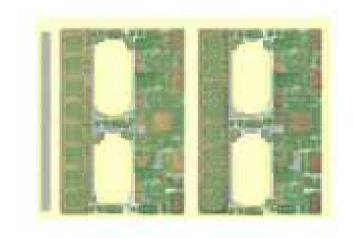


2)high thermal conductivity coefficient

FR4:0.2-0.3

RT1755:0.6-0.7

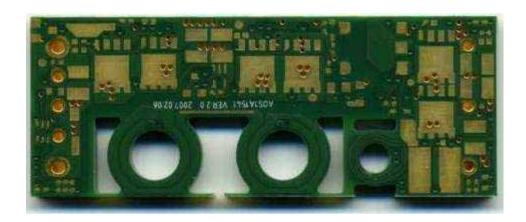
Arlon99:1.0





3)Heavy copper PCBs: 3oz-6oz

for High current density



Pic from: http://www.somacisgraphic.com/cn/msg.php?id=13



4. Module package

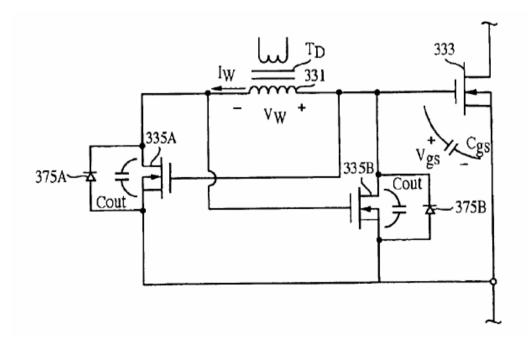


- 1) distributing hot point
- 2)minimizing the size
- 3) ease the safty standard



5. Low loss gate drive

Vicor patent, US6911848







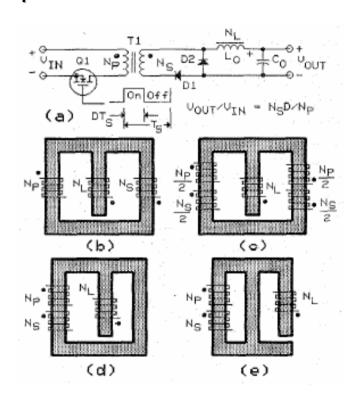
6. Magnetic Integration







2)other benefits: efficiecy /current ripple/parasitical parameters



Reference:

IEEE TRANSACTIONS ON MAGNETICS, VOL. 34, NO. 4, JULY 1998

New Multi-Chambered Power Magnetics Concepts

e/j BLOOM associates Inc., Product Engineering Division 4340 Redwood Highway, Office E356 San Rafacl. CA 94903 U.S.A.



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Fourth. Summary

Trend 1: High frequency

1/16 B->1/32 B; soft switch & low-loss gate drive

Trend 2: Digital control

efficiency; analogy parts number; improve power density; advanced Loop control; intelligence power manager (efficiency & fault)

Trend 3: Advanced package & materials

minimizing size and improve heat performance buried resister and capacitor; minimizing parasitical parameters

Trend 4: Flat Magnetic & magnetic integration

minimizing core size; improve efficiency and others



Thanks!

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